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REVISION HISTORY						
REV	DOI NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	DATE
00	N/A	INITIAL RELEASE	JROWE	N/A	N/A	04/05/05
01	N/A	CORRECT A1 BALL PAD INDICATOR ON TOP	JROWE	N/A	N/A	04/07/05

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

2. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		Amkor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Amkor Technology Philippines, Inc., Cebu, Philippines	
DECIMAL X.XX ±0.105	ANGULAR ±1°	APPROVALS	DATE	PACKAGE OUTLINE, PS-vfBGA 305, 12.00mm X 12.00mm, 9.00SQ MOLD CAP, 0.50mm PITCH, LAMINATE SUBSTRATE, AWW	
X.XX ±0.030		DESIGNED JROWE	04/01/05	SIZE A3	SHEET 1 OF 2
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994		CHECKED ACOP1	04/01/05	SD NUMBER	REV
SEE CROSS SECTION		PRODUCT MANAGER MDREI	04/01/05	DWG NUMBER 320441	01
FINISH SEE NOTE 1		RELEASED SLOWD	04/05/05	STRIP DWG NUMBER/REV N/A	
DO NOT SCALE DRAWING				PWG OUTLINE DWG NO. N/A	
				SCALE NONE	